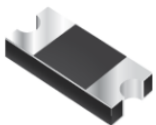


MATERIAL DECLARATION SHEET



| | | | | |
|-----------------|------------------------|-----|---|---|
| Material Number | CD214A-R12000R | | |  |
| Product Line | Semiconductor Products | | | |
| Compliance Date | 2019/8/2 | | | |
| RoHS Compliant | Yes | MSL | 1 | |

| No. | Construction Element(subpart) | Homogeneous Material | Material weight [mg] | Homogeneous Material\ Substances | CASRN if applicable | Materials Mass % | Material Mass % of total unit wt. | Subpart mass of total wt. (%) |
|-----|-------------------------------|----------------------|----------------------|----------------------------------|---------------------|------------------|-----------------------------------|-------------------------------|
| 1 | FRP | Metal | 12.01 | Continuous filament glass fibers | 65997-17-3 | 25.10% | 15.072550% | 60.05% |
| | | | | Phosphorus-based epoxy resin | Confidentiality | 23.11% | 13.877555% | |
| | | | | Inorganic filler | Confidentiality | 12.07% | 7.248035% | |
| | | | | Copper | 7440-50-8 | 39.45% | 23.689725% | |
| | | | | Zinc | 7440-66-6 | 0.20% | 0.120100% | |
| | | | | Nickel | 7440-02-0 | 0.05% | 0.030025% | |
| | | | | Chromium | 7440-47-3 | 0.01% | 0.006005% | |
| 2 | Epoxy | Plastic | 4.23 | Arsenic | 7440-38-2 | 0.01% | 0.006005% | 21.15% |
| | | | | Silicon Dioxide | 7631-86-9 | 57.14% | 12.085110% | |
| 3 | Die Attach | Metal | 0.25 | Bis-Phenol Type Epoxy | 9003-36-5 | 42.86% | 9.064890% | 1.25% |
| | | | | Lead ^(Note 2) | 7439-92-1 | 92.5% | 1.156250% | |
| 4 | Dice | Others | 3.11 | Tin | 7440-31-5 | 5.0% | 0.062500% | 15.55% |
| | | | | Silver | 7440-22-4 | 2.5% | 0.031250% | |
| | | | | Silicon | 7440-21-3 | 73.54% | 11.4354690% | |
| | | | | Nickel | 7440-02-0 | 1.99% | 0.3094450% | |
| | | | | Aluminum | 7429-90-5 | 0.56% | 0.0870800% | |
| | | | | Lead Glass ^(Note 3) | 7439-92-1 | 14.80% | 2.3014000% | |
| 5 | Terminal Plating | Metal | 0.4 | Phosphorus | 7723-14-0 | 0.249% | 0.0387200% | 2.00% |
| | | | | Boron | 7440-42-8 | 0.874% | 0.1359070% | |
| | | Total weight | 20 | Misc., not to declare | Confidentiality | 7.987% | 1.2419790% | |
| | | | | Tin | 7440-31-5 | 100% | 2.000000% | |

MATERIAL DECLARATION SHEET



This Document was updated on: 2019/8/2

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. RoHS exemption 7(a): Lead in high melting temperature type solders (i.e. lead- based alloys containing 85% by weight or more lead)
3. RoHS exemption 7(c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezo-electronic devices, or in a glass or ceramic matrix compound